

Title (en)
INTERFACE MATERIALS AND METHODS OF PRODUCTION AND USE THEREOF

Title (de)
GRENZFLÄCHENMATERIALIEN UND HERSTELLUNGSVERFAHREN UND VERWENDUNG DAVON

Title (fr)
MATERIAUX D'INTERFACE ET LEURS PROCEDES DE PRODUCTION ET D'UTILISATION

Publication
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Application
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Priority

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Abstract (en)
[origin: WO02096636A1] Layered interface materials described herein comprise at least one crosslinkable thermal interface component and at least one compliant fibrous interface component coupled to the thermal interface component. A method of forming layered interface materials comprises: a) providing a crosslinkable thermal interface component; b) providing a compliant fibrous interface component; and c) physically coupling the thermal interface component and the compliant fibrous interface component. At least one additional layer, including a substrate layer, can be coupled to the layered interface material.

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CPC (source: EP KR US)
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Citation (search report)

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WO 02096636 A1 20021205; CA 2433637 A1 20021205; CN 1267268 C 20060802; CN 1512933 A 20040714; EP 1401641 A1 20040331; EP 1401641 A4 20071212; JP 2005508767 A 20050407; JP 4237505 B2 20090311; KR 20040002866 A 20040107; TW I286514 B 20070911

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